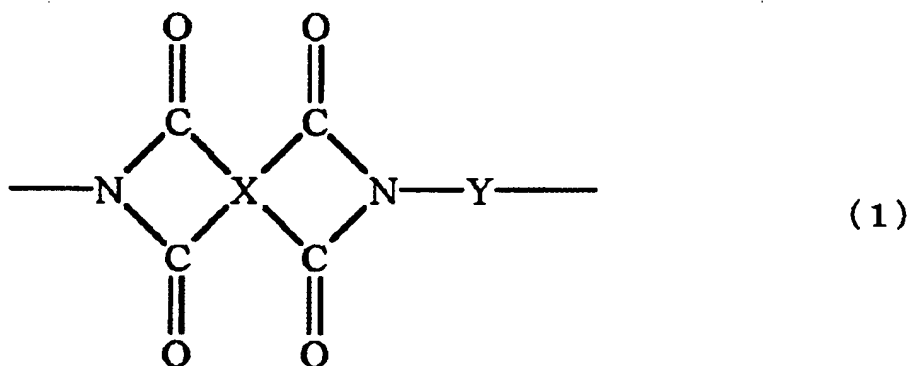
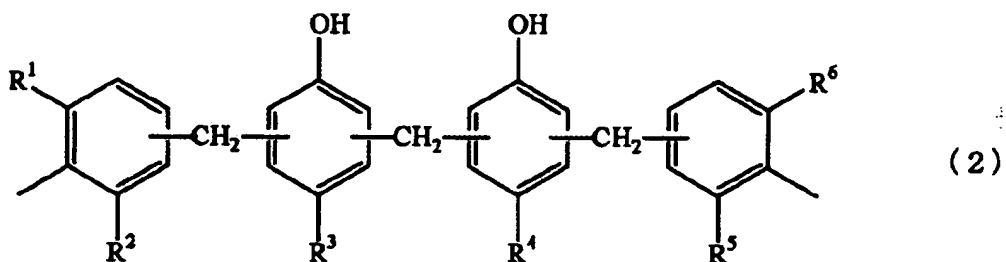


AMENDMENTS TO THE CLAIMS

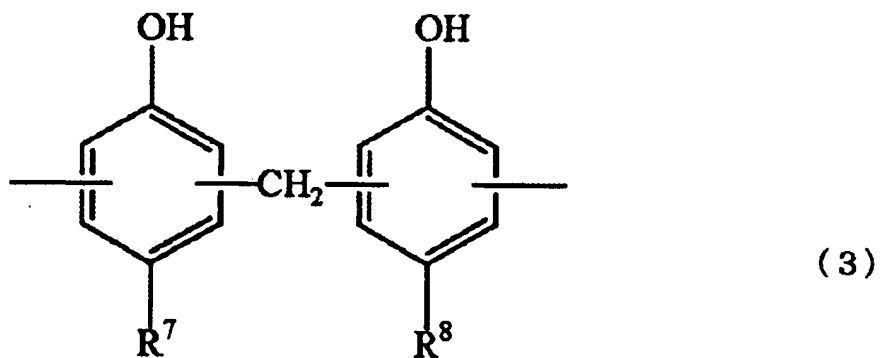
1. (currently amended) A colorless and transparent thermosetting polyimidesilicone resin comprising structural units of the following general formula (1) and structural units of the general formula (4), said resin being soluble in an organic solvent



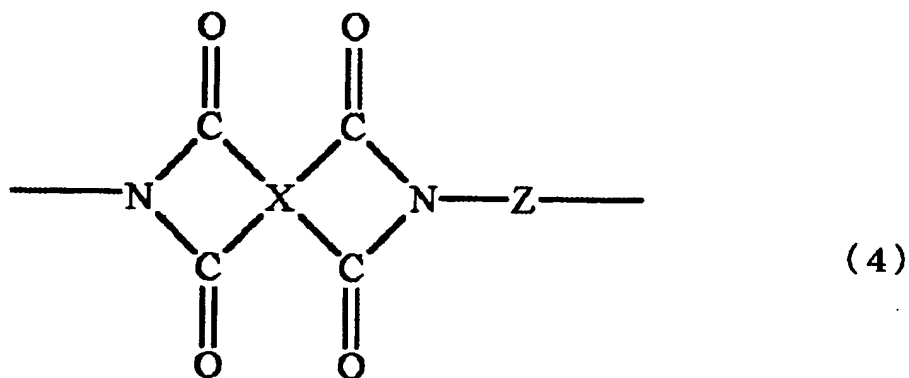
wherein X is a tetravalent organic group having 4 or more carbon atoms, none of the carbon atoms of X being bound to a plurality of carbonyl groups, said tetravalent organic group being derived from the group consisting of aliphatic tetracarboxylic dianhydrides, alicyclic tetracarboxylic dianhydrides, and aromatic tetracarboxylic dianhydrides, with said aromatic tetracarboxylic dianhydrides being in such an amount that they do not cause discoloration of the polyimidesilicone resin, and Y is a diamine residue of the general formula (2) or (3),



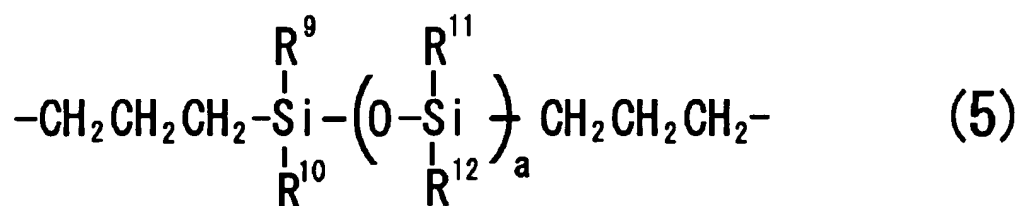
wherein each of R^1 , R^2 , R^3 , R^4 , R^5 and R^6 is independently selected from the group consisting of a hydrogen atom and alkyl groups having 1 to 6 carbon atoms,



wherein each of R^7 and R^8 is independently selected from the group consisting of a hydrogen atom and alkyl groups having 1 to 6 carbon atoms;



wherein X is a tetravalent organic group having 4 or more carbon atoms, none of the carbon atoms of X being bound to a plurality of carbonyl groups, said tetravalent organic group being derived from the group consisting of aliphatic tetracarboxylic dianhydrides, alicyclic tetracarboxylic dianhydrides, and aromatic tetracarboxylic dianhydrides, with said aromatic tetracarboxylic dianhydrides being in such an amount that they do not cause discoloration of the polyimidesilicone resin, and Z is a diamine residue of the general formula (5),



wherein each of R^9 , R^{10} , R^{11} , and R^{12} is independently selected from the group consisting of substituted or unsubstituted monovalent hydrocarbon groups having 1 to 8 carbon atoms, and "a" is an integer of from 1 to 100.

2. (original) The polyimidesilicone resin according to claim 1, wherein an amount of the diamine residue of the general formula (2) or (3) ranges from 5 mole % to 95 mole % and an amount of the diamine residue of the general formula (5) ranges from 5 mole % to 95 mole %, based on the total amount of the diamine residues.

3. (original) The polyimidesilicone resin according to claim 1 or 2, wherein the resin has a transmittance of 80 % or higher in the wavelength region of from 400 nm to 700 nm, measured in a form of a film of 10 μ m thickness on a glass substrate of 1 mm thickness.

4. (withdrawn - currently amended) A semiconductor device or a display apparatus which comprises polyimidesilicone resin according to claim 1 ~~any one of claims 1 to 3 is used.~~

5. (new) A semiconductor device or a display apparatus which comprises polyimidesilicone resin according to claim 2.

6. (new) A semiconductor device or a display apparatus which comprises polyimidesilicone resin according to claim 3.

7. (new) The polyimidesilicone resin according to claim 1, wherein said tetravalent organic group is derived from the group consisting of butane-1,2,3,4-tetracarboxylic dianhydride, pentane-1,2,3,4-tetracarboxylic dianhydride, 1,2,3,4-cyclobutanetetracarboxylic dianhydride, cyclohexane-1,2,3,4-tetracarboxylic dianhydride, dicyclohexyl-3,4,3',4'-tetracarboxylic dianhydride, bicyclo[2.2.1]heptane-2,3,5,6-tetracarboxylic dianhydride, 2,3,4,5-tetrahydrofuran-tetracarboxylic dianhydride, pyromellitic dianhydride, 3,3',4,4'-benzophenonetetracarboxylic dianhydride, 3,3',4,4'-diphenyl ether tetracarboxylic dianhydride, 4,4'-hexafluoropropylidenebisphthalic dianhydride, 3,3',4,4'-diphenyl sulfone tetracarboxylic dianhydride, 3a,4,5,9b-tetrahydro-5-(tetrahydro-2,5-dioxo-3-furanyl)-naphtho[1,2-c]furan-1,3-dione, and 3a,4,5,9b-tetrahydro-5-methyl-5-(tetrahydro-2,5-dioxo-3-furanyl)-naphtho[1,2-c]furan-1,3-dione.

8. (new) The polyimidesilicone resin according to claim 1, prepared by reacting 3a,4,5,9b-tetrahydro-5-(tetrahydro-2,5-dioxo-3-furanyl)-naphtho[1,2-c]furan-1,3-dione with 2,2'-methylenebis[6-(4-amino-3,5-dimethylbenzyl)-4-methyl]phenol and then with a diaminosiloxane of the general formula (5) wherein "a" is 9.5 on average.

9. (new) The polyimidesilicone resin according to claim 1, prepared by reacting 3a,4,5,9b-tetrahydro-5-(tetrahydro-2,5-dioxo-3-furanyl)-naphto[1,2-c]furan-1,3-dione with 2,2'-methylenebis[6-(4-amino-3,5-dimethylbenzyl)-4-methyl]phenol and then with a diaminosiloxane of the general formula (5) wherein "a" is 9.5 on average.

10. (new) The polyimidesilicone resin according to claim 1, prepared by reacting 3a,4,5,9b-tetrahydro-5-(tetrahydro-2,5-dioxo-3-furanyl)-naphto[1,2-c]furan-1,3-dione with 2,2'-methylenebis[6-(4-amino-3,5-dimethylbenzyl)-4-methyl]phenol and then with a diaminosiloxane of the general formula (5) wherein "a" is 9.5 on average.